

ABSTRACT

(Figure 1)

ALUMINIUM NITRIDE CERAMICS AND METHOD FOR PREPARING THE SAME

Aluminium nitride ceramics improved in heat radiation property used as a substrate for integrated circuits and package material, comprising a sintered article consisting mainly of aluminium nitride and having a thermal conductivity higher than $100 \cdot \text{W/m} \cdot \text{K}$ at room temperature and a surface layer consisting mainly of aluminium nitride or oxide glass deposited on the sintered article.

A paste of aluminium nitride powder or oxide glass powder is coated on a surface of the sintered article of aluminium nitride and then is sintered to prepare a dense smooth surface layer.